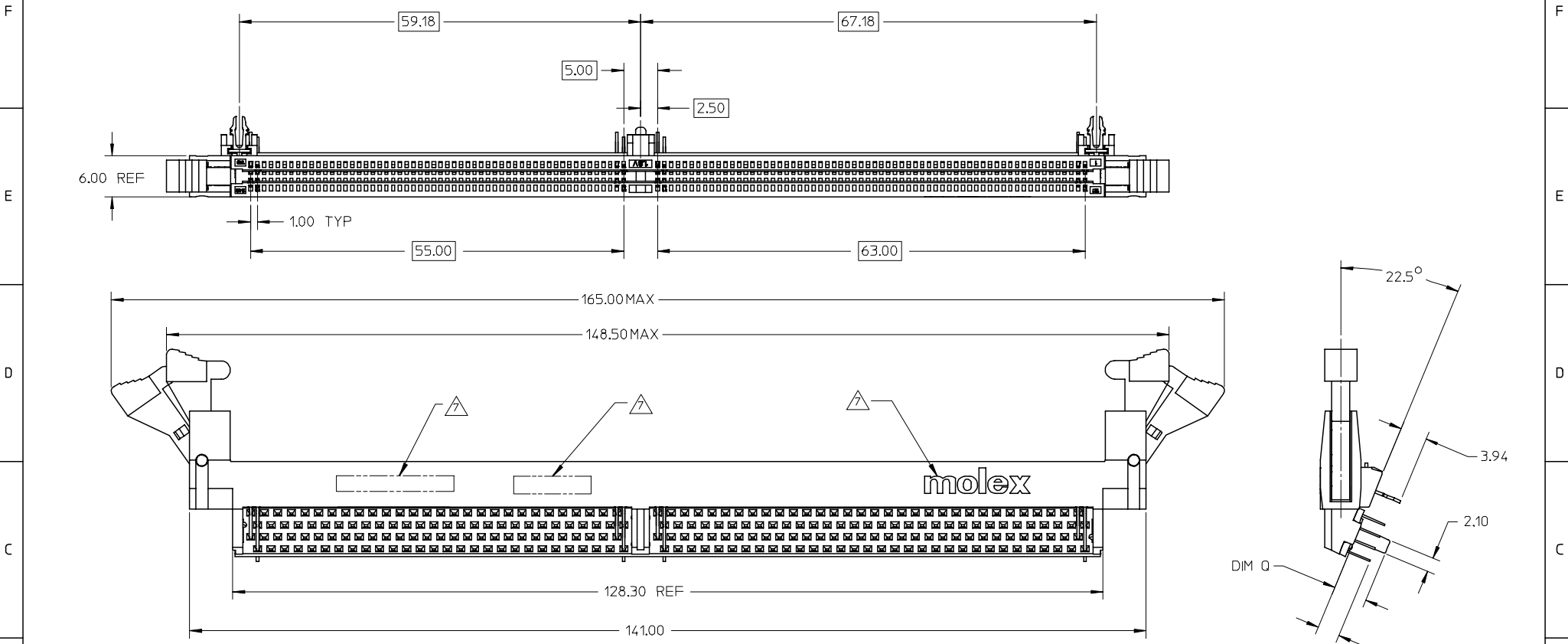


10 9 8 7 6 5 4 3 2 1



- NOTES :
- MATERIALS : HOUSING, BASEPLATE AND LATCH.
- HIGH TEMP THERMOPLASTIC, UL94-0.
TERMINALS & FORKLOCK - COPPER ALLOY.
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
SOLDERTAIL - SEE TABLE IN SHEET 5.
 - CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS
(MEASURED OVER PC PADS).
 - REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR
PERFORMANCE SPECIFICATION.
 - RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 - PRODUCT SHALL BE PACKED IN TRAY.
- ▲ MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

ADDED OPTION EC NO: S2008-0329 DRWN:CTEH CHKD:TYANG01 APPR:SHLENI 2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	JTAN	2004/05/11	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	
2 PLACES	± 0.25	± ---	2 PLACES	± ---	MLONG	2004/06/11		
1 PLACE	± ---	± ---	1 PLACE	± ---	APPROVED BY	DATE		
		ANGULAR ± 5 °		GGLEE	2004/06/11	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO.	SHEET NO.	
						SD-87916-001	1 OF 5	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

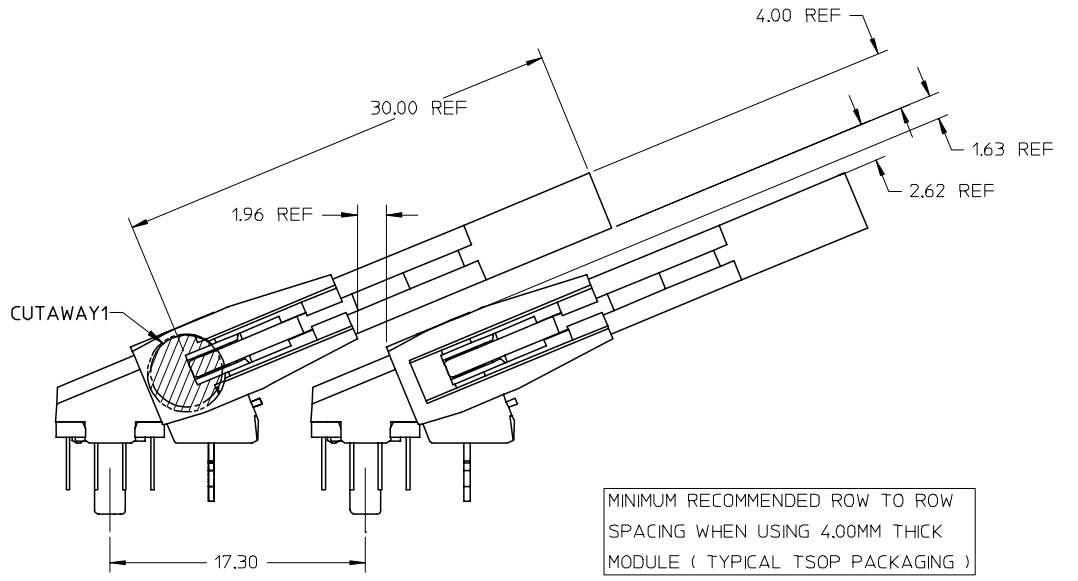
C

B

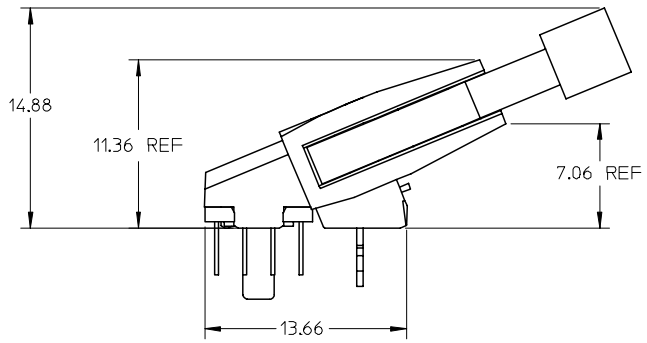
B

A

A

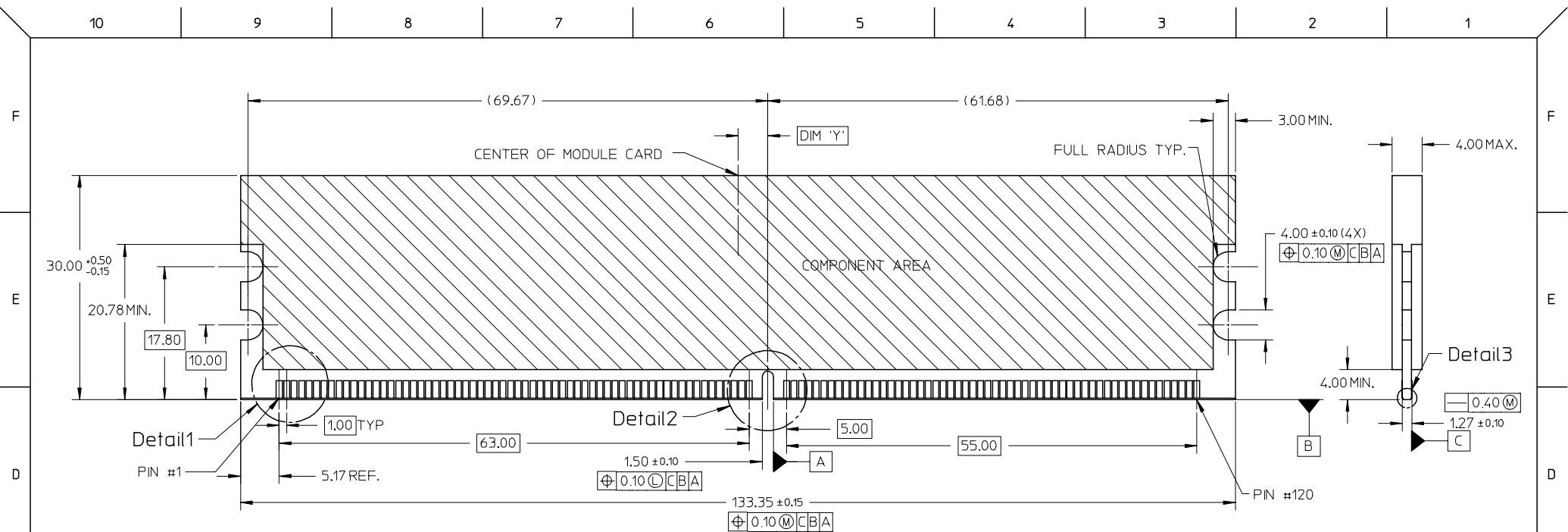


MINIMUM RECOMMENDED ROW TO ROW SPACING WHEN USING 4.00MM THICK MODULE (TYPICAL TSOP PACKAGING)

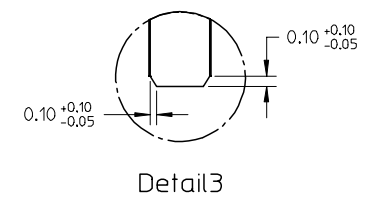
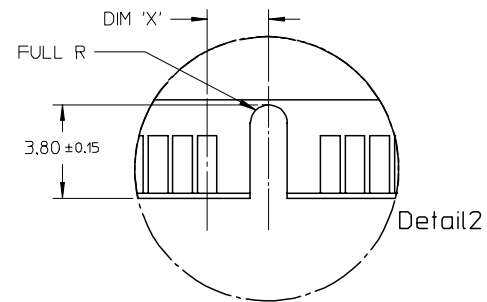
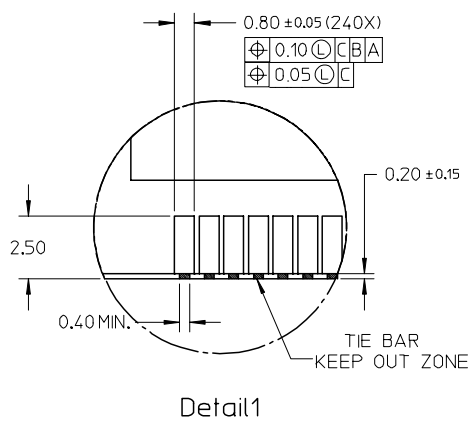


ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	2007/10/24		4 PLACES	± ---	± ---	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
	2007/10/25		3 PLACES	± ---	± ---	CHECKED BY MLONG	DATE 2004/06/11				
			2 PLACES	± 0.25	± ---	APPROVED BY GGLEE	DATE 2004/06/11	MOLEX INCORPORATED DOCUMENT NO. SD-87916-001		SHEET NO. 2 OF 5	
A1	REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

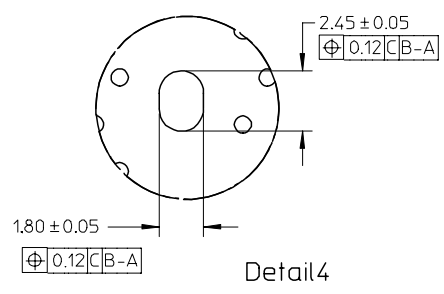
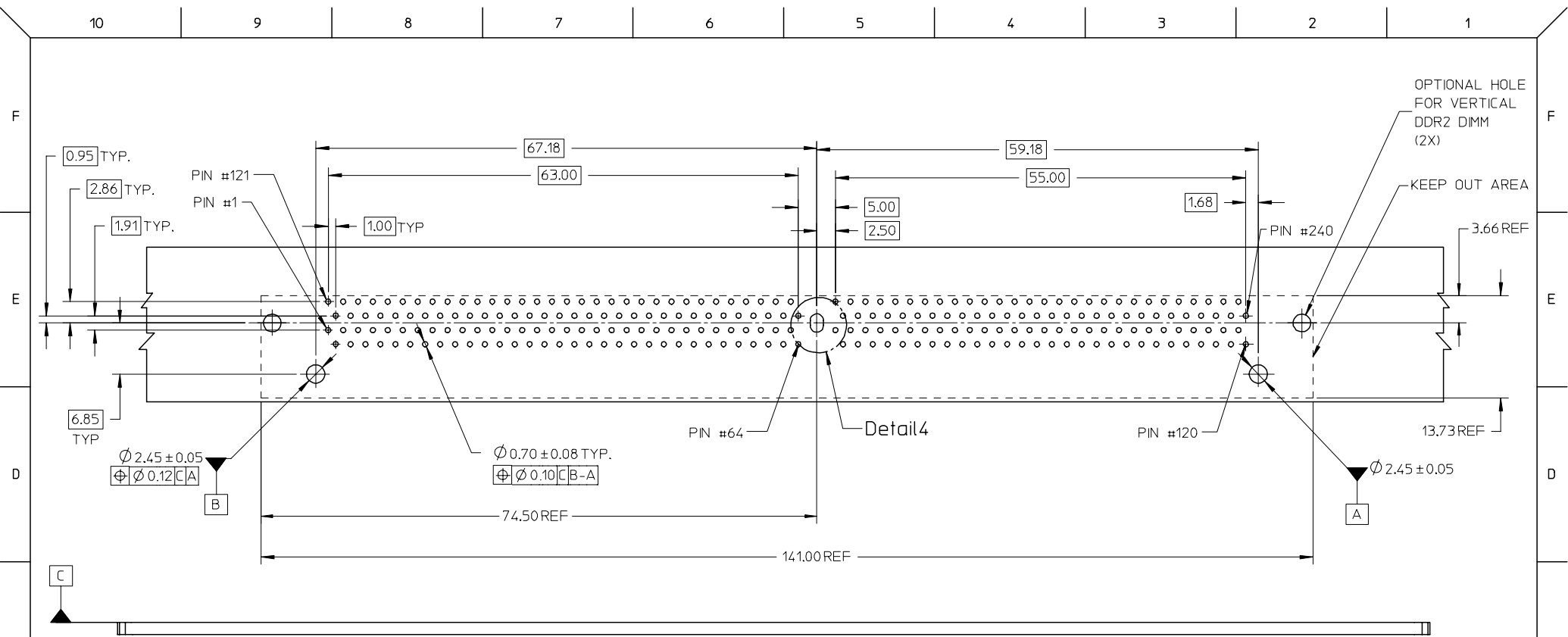


RECOMMENDED MODULE LAYOUT



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

ADDED OPTION EC NO: S2008-0329 DRWN: CTEH CHKD: TYANG01 APPR: SILENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG				
					CHECKED BY MLONG	DATE 2004/06/11	MOLEX INCORPORATED				
					APPROVED BY GGLEE	DATE 2004/06/11	SEE TABLE		DOCUMENT NO. SD-87916-001	SHEET NO. 3 OF 5	
A1		DESCRIPTION REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



ADDED OPTION	2007/10/24
EC NO: S2008-0329	2007/10/24
DRWN: CTEH	2007/10/24
CHKD: TYANG01	2007/10/25
APPR: SILENI	
REV	DESCRIPTION
A1	

QUALITY SYMBOLS	$\nabla = 0$
	$\nabla C = 0$

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
	4 PLACES ± ---	± ---
	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
JTAN	2004/05/11	DDR2 DIMM, 1.00MM PITCH		
CHECKED BY	DATE	240 CKTS, 22.5 DEG		
MLONG	2004/06/11			
APPROVED BY	DATE			
GGLEE	2004/06/11			
MATERIAL NO.	DOCUMENT NO.			
	SD-87916-001			
SIZE	SEE TABLE			
A3				

MOLEX INCORPORATED		SHEET NO.
		4 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

C

B

B

A

A

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'O'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76μm/ 30μ" GOLD OVER 1.27μm/ 50μ" MIN NICKEL	2.54μm/ 100μ" MIN. TIN OVER 1.27μm/ 50μ" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

ADDED OPTION EC NO: S2008-0329 DRWN:CTEH CHKD:TYANG01 APPR:SHLENI	2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
									TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG		
									MOLEX INCORPORATED		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		DOCUMENT NO. SD-87916-001		SHEET NO. 5 OF 5	

9 8 7 6 5 4 3 2 1